

## **D. Research Areas in IC Package Design & Development**

<b>D.1</b>	<b>Design &amp; Development of Advanced Packages (single chip, MCM-C, MCM-D, MCM-L, SiP) for ICs in HTCC, LTCC, Si substrate, laminates</b>
<b>D.2</b>	<b>Signal Integrity and Power Integrity aspects for optimum interconnect performance on ceramic and Si substrate</b>
<b>D.3</b>	<b>Thermo-mechanical aspects in IC packages for high power dissipation dies / power dies</b>